

CLAIMS

What is claimed:

1. A stackable layer comprised of:

A substrate having an active surface and an inactive surface, said active surface having active circuitry formed thereon, said active circuitry including at least one bond pad; means for electrically connecting said bond pad to a predefined location on said inactive surface.

2. The stackable layer of Claim 1 wherein said electrical connection means comprises at least one via defined in said substrate, said via including an electrically conductive material.

3. The stackable layer of Claim 2 wherein said electrically conductive material is a tungsten material.

4. A stackable layer comprised of:

A substrate having a first surface and a second surface, said first surface having at least one electrical connection point formed thereon, means for electrically connecting said electrical connection point to a predefined location on said inactive surface.

5. The stackable layer of claim 4 wherein said electrical connection means includes at least one via, said via including an electrically conductive material.

6. The stackable layer of Claim 5 wherein said electrically conductive material is a tungsten material.

7. A ministack comprised of:

A first substrate having an active surface and an inactive surface, said active surface having active circuitry formed thereon, said active circuitry including at least one bond

pad; means for electrically connecting said bond pad to a predefined location on said inactive surface; a second substrate with an active surface with active circuitry formed thereon, said active circuitry of said second substrate including at least one electrical contact point; means for electrical interconnection of said predefined location on said first substrate with said at least one electrical contact point of said second substrate; said first substrate and said second substrate bonded together to form a stack.

8. The ministack of Claim 7 wherein said electrical contact point is a via, said via including an electrically conductive material.

9. The ministack of Claim 8 wherein said electrical contact point is a bond pad in electrical communication with said active circuitry of said second substrate.

10. The ministack of claim 8 wherein said first substrate electrical connection means includes at least one via defined in said first substrate, said via including an electrically conductive material.

11. The ministack of Claim 8 wherein said electrically conductive material is a tungsten material.

12. A stacked electronic module comprised of:

at least two ministacks of Claim 7; means for electrical interconnection of each of said at least two ministacks.

13. The stacked electronic module of Claim 12 wherein said electrical interconnection means comprises at least one via filled with an electrically conductive material defined in at least one of said at least two ministacks.

14. The stacked electronic module of Claim 13 wherein said electrically conductive material is a tungsten material.